



Product Change Notice

Micron PCN: 31181
 Date: 3/3/2014

Type of Change:	Manufacturing Site Change	
Title of Change:	512Mb 50nm DDR1 (T67A) and DDR2 (U67A) Fab Site Transition (from Singapore to Virginia, USA)	
Description of Change:	Fabrication of Micron's 50nm 512Mb DDR1 (T67A) and DDR2 (U67A) parts will move from Singapore (Fab 7) to Virginia, USA (Fab 6).	
Reason for Change:	Optimization of Manufacturing Efficiency	
Contact Information:	<u>Marketing Contact</u> DAN COMBE Micron Semiconductor Prds DCOMBE@MICRON.COM	<u>Engineering Contact</u> DENZIL ROGERS Micron Semiconductor Prds DENZILROGERS@MICRON.COM

Product Affected: All T67A and U67A parts

Affected Micron Part Number

T67A (DDR1)

Components

MT46V32M16CY-5B IT:J	MT46V64M8CY-5B:J	MT46V64M8P-5B IT:J
MT46V32M16CY-5B L IT:J	MT46V64M8P-5B:J	MT46V64M8CY-5B L:J
MT46V32M16CV-5B IT:J	MT46V64M8TG-5B IT:J	MT46V32M16CY-5B:J
MT46V32M16P-5B IT:J	MT46V64M8TG-5B:J	MT46V32M16TG-5B IT:J
MT46V32M16P-5B L:J	MT46V64M8CV-5B:J	MT46V128M4P-5B:J
MT46V32M16P-5B:J	MT46V64M8CV-5B IT:J	MT46V64M8P-6T:J
MT46V32M16TG-5B:J	MT46V128M4CY-5B:J	MT46V256M4SP-5B:J
MT46V64M8P-5B L IT:J	MT46V128M4CV-5B:J	
MT46V64M8CY-5B IT:J	MT46V32M16CV-5B:J	

Modules

MT18VDDF12872Y-40BJ1	MT18VDDF12872HY-40BJ1	MT8VDDT6464HDY-335J1
MT4VDDT3264HY-40BJ1	MT16VDDF12864HY-40BJ1	MT9VDDT6472PHY-335J1
MT9VDDT6472HY-40BJ1	MT9VDVF6472Y-40BJ1	MT18VDDF12872DG-335J1
MT8VDDT6464HDY-40BJ1	MT16VDDF12864AY-40BJ1	MT18VDDF12872HY-335J1
MT9VDDT6472AY-40BJ1	MT18VDDF12872DY-335J1	MT8VDDT6464HY-335J1
MT18VDDT12872AY-40BJ1	MT9VDDF6472Y-335J1	MT8VDDF6464AY-40BJ1
MT4VDDT3264AY-40BJ1	MT8VDDT12832UY-40BJ1	MT4VDDT3264HY-335J1
MT36VDDF25672Y-40BJ1	MT18VDVF12872DY-335J1	MT9VDDT6472HY-335J1
MT9VDDF6472Y-40BJ1	MT36VDDF25672Y-335J1	

Die/Wafer

MT46V128M4T67A3WC1	MT46V64M8T67A3WC1
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Affected Micron Part Number

U67A Parts**Components**

MT47H32M16HR-25E:G	MT47H32M16HR-25E IT:G	MT47H64M8CF-25E L:G
MT47H32M16HR-3:G	MT47H32M16HW-25E:G	MT47H64M8JN-25E IT:G
MT47H128M4CF-25E:G	MT47H64M8JN-25E:G	MT47H32M16HR-25E L:G
MT47H64M8CF-25E:G	MT47H32M16HW-25E IT:G	MT47H32M16HR-187E:G
MT47H64M8CF-3:G	MT47H64M8CF-25E IT:G	

Modules

MT18HTF12872AZ-80EG1	MT36HTF25672PZ-667G1	MT4HTF3264HZ-667G1
MT4HTF3264HZ-800G1	MT9HVF6472PZ-667G1	MT18HTF12872Z-40EG1
MT18HTF12872FDZ-667G1D6	MT9HTF6472PKZ-667G1	MT18HTF12872PZ-667G1
MT9HTF6472PZ-667G1	MT18HTF12872PDZ-667G1	MT16HTF12864AZ-800G1
MT9HTF6472RHZ-667G1	MT16HTF12864HZ-667G1	
MT9HVF6472PKZ-667G1	MT8HTF6464HDZ-667G1	

Die/Wafer

MT47H32M16U67A3WC1	MT47H64M8U67A3WC1
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Method of Identification:

Component Mark: The first character in the "country of diffusion-encapsulation" code in the component mark for product fabricated will change from "2" (Singapore) to "1" (USA). Please refer to Micron Customer Service Note-11 for detailed description of marking codes

Micron Sites Affected: Micron Manassas (MTV),Micron Singapore (MSA),Micron Singapore(Tech)

Sample Available: Now

Qual Data Available: Now

Product Ship Date: May 2014
